ABSTRACT

SEMICONDUCTOR MULTI-PACKAGE MODULE HAVING INVERTED LAND GRID ARRAY (LGA) PACKAGE STACKED OVER BALL GRID ARRAY (BGA) PACKAGE

A semiconductor multi-package module has a second package inverted and stacked over a first package, each of the packages having a die attached to a substrate, in which the second package substrate and the first package substrate are interconnected by wire bonding, and in which the first package includes a ball grid array package. Also, a method for making a semiconductor multi-package module, by providing a lower molded ball grid array package including a lower substrate and a die, affixing an upper molded package including an upper substrate in inverted orientation onto the upper surface of the lower package, and forming z-interconnects between the upper and lower substrates.